

Part Number: XZMDK55W-A2

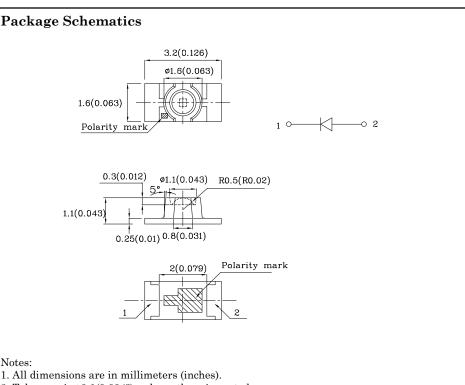
3.2x1.6mm SMD CHIP LED LAMP

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

Notes:

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Red (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	\mathbf{I}_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA	
Power Dissipation	PD	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	$-40 \sim +85$	U	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

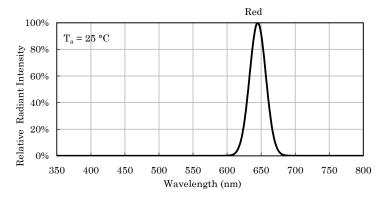
Operating Characteristics (T _A =25°C)	Red (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.95	v
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	v
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	28	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous CIE127 (I _F =20 mo	-2007*)mA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMDK55W-A2	Red	AlGaInP	Water Clear	400 120*	547 228*	645*	80°

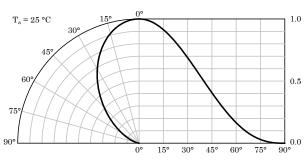
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



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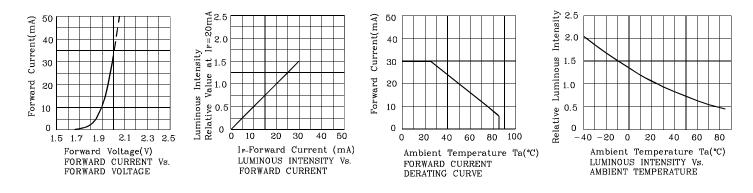


Relative Intensity Vs. CIE Wavelength

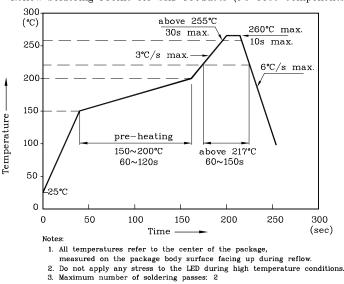


Spatial Distribution

Red



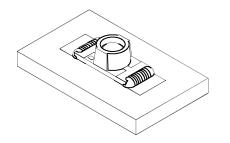
LED is recommended for reflow soldering and soldering profile is shown below.



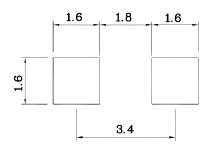
Reflow Soldering Profile for SMD Products (Pb-Free Components)



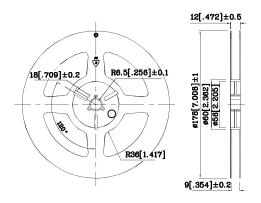
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



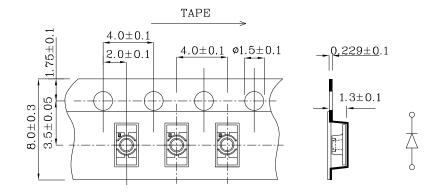
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

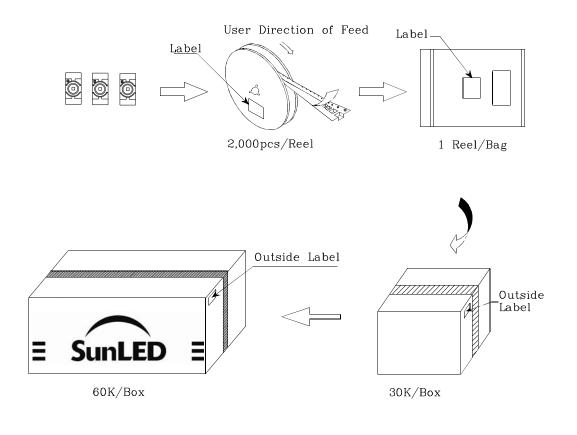
3. Forward Voltage: +/-0.1V $\,$

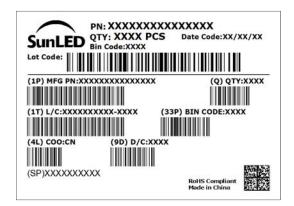
Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS





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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at <u>https://www.SunLEDusa.com/TechnicalNotes.asp</u>

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